

This Page Is Inserted by IFW Operations
and is not a part of the Official Record

BEST AVAILABLE IMAGES

Defective images within this document are accurate representations of the original documents submitted by the applicant.

Defects in the images may include (but are not limited to):

- BLACK BORDERS
- TEXT CUT OFF AT TOP, BOTTOM OR SIDES
- FADED TEXT
- ILLEGIBLE TEXT
- SKEWED/SLANTED IMAGES
- COLORED PHOTOS
- BLACK OR VERY BLACK AND WHITE DARK PHOTOS
- GRAY SCALE DOCUMENTS

IMAGES ARE BEST AVAILABLE COPY.

**As rescanning documents *will not* correct images,
please do not report the images to the
Image Problem Mailbox.**

The following Listing of Claims will replace all prior versions, and listings, of claims in the application.

LISTING OF CLAIMS:

1. (Currently amended) A method for drying substrates ~~is a method which houses substrates within a processing vessel, and dries a surface of each of the substrates by relatively comprising:~~

~~housing substrates within a processing vessel containing a cleaning fluid; lowering a fluid face of the cleaning fluid within [[a]] the processing vessel with respect to the substrates; and by introducing the cleaning fluid within the processing vessel, the method comprising the steps of,~~

~~Introducing introducing a drying fluid under a liquid condition within the processing vessel [[, and]] using a nozzle with the nozzle Forming forming individual liquid drops of the drying fluid and supplying the liquid drops onto the fluid face of the cleaning fluid using a nozzle.~~

2. (Currently Amended) A method for drying substrates as set forth in claim 1, wherein

~~the method houses the substrates within the processing vessel in an inclined condition by at a predetermined angle with respect to a vertical plane, and supplies the liquid drops of the drying fluid using the nozzle in a direction with the nozzle inclined at an inclination angle which is the same direction substantially similar to the predetermined angle of the inclined substrates.~~

3. (Currently Amended) A method for drying substrates as set forth in claim 1, wherein

~~the method determines an introduction direction of the drying fluid into the processing vessel and determines an introduction initial speed of the drying fluid so as to expand the drying fluid up to the an entire width of the substrates on the fluid surface of the cleaning fluid.~~

4. (Currently Amended) A method for drying substrates as set forth in claim 1, wherein

the method supplies inert gas into the processing vessel following exhausting of the cleaning fluid from the processing vessel.

5. (Currently Amended) A method for drying substrates as set forth in claim 4, wherein

the method increases ~~the a~~ supplying quantity of the drying fluid and/or the inert gas into the processing vessel following exhausting of the cleaning fluid from the processing vessel.

6. (Currently Amended) A method for drying substrates as set forth in claim 1, wherein

the method changes supporting positions of the substrates following exhausting of the cleaning fluid from the processing vessel.

7. (Currently Amended) A method for drying substrates as set forth in claim 4, wherein

the method makes ~~the an~~ interior of the processing vessel ~~to be an~~ inert gas environment prior to exhausting of the cleaning fluid from the processing vessel.

8. (Currently Amended) A method for drying substrates as set forth in claim 1, wherein

the method carries out the ~~cleaning process and the following drying process lowering of the fluid face of the cleaning fluid and the introducing of the drying fluid in the liquid condition under at a room temperature.~~

9. (Currently Amended) A method for drying substrates as set forth in claim 1, wherein

the method supplies inert gas to the nozzle, and flows the drying fluid by ~~the a~~ pressure of the inert gas which is supplied to the nozzle.

10. (Currently Amended) A device for drying substrates ~~is a device which supports substrates within a processing vessel by supporting means, and dries a surface of each of the substrates by relatively lowering a fluid face of cleaning fluid within a processing vessel with respect to the substrate and by introducing the cleaning fluid within the processing vessel, the device comprising~~[[,]]:

a processing vessel containing a cleaning fluid;

means for supporting substrates within the processing vessel;

means for relatively lowering a fluid face of the cleaning fluid within the processing vessel with respect to the substrates; and

Drying fluid supplying means for introducing a drying fluid under a liquid condition within the processing vessel using a nozzle with the nozzle, for forming individual liquid drops of the drying fluid using a nozzle, and for supplying the liquid drops of the drying fluid onto the fluid face of the cleaning fluid using a nozzle.

11. (Currently Amended) A device for drying substrates as set forth in claim 10, wherein

the supporting means is the means for supporting substrates supports the substrates within the processing vessel in an inclined condition by at a predetermined angle with respect to a vertical plane, and the nozzle is a nozzle for supplying supplies the liquid drops of the drying fluid using the nozzle in a direction with the nozzle inclined at an inclination angle which is the same direction substantially similar to the predetermined angle of the inclined substrates.

12. (Currently Amended) A device for drying substrates as set forth in claim 10, wherein

the means for introducing the drying fluid supplying means is a means for determining determines an introduction direction of the drying fluid into the processing vessel and determines an introduction initial speed of the drying fluid so as to expand the drying fluid up to the an entire width of the substrates on the fluid surface of the cleaning fluid.

13. (Currently Amended) A device for drying substrates as set forth in claim 10, further comprising

~~inert gas supplying~~ means for supplying inert gas into the processing vessel following exhausting of the cleaning fluid from the processing vessel.

14. (Currently Amended) A device for drying substrates as set forth in claim 13, further comprising

~~supplying quantity control~~ means for increasing ~~the a~~ supplying quantity of the drying fluid and/or the inert gas into the processing vessel following exhausting of the cleaning fluid from the processing vessel.

15. (Currently Amended) A device for drying substrates as set forth in claim 10, wherein

~~the means for supporting means is a means having a substrates includes an upper face with a plurality of supporting grooves therein, and a cleaning fluid introduction groove which follows in lower ward extends from a bottom section of each of the supporting grooves in a downward direction with respect to the upper face the substrate supporting section.~~

16. (Currently Amended) A device for drying substrates as set forth in claim 10, wherein

~~the supporting means for supporting substrates is a pair of supporting means members for selectively supporting different positions of the substrates which at different supporting positions are different from one another, and the device for drying substrates further comprising comprises supporting position control means for changing the supporting positions of the substrates by the supporting means following exhausting of the cleaning fluid from the processing vessel.~~

17. (Currently Amended) A device for drying substrates as set forth in claim 13, further comprising

~~environment determination~~ means for making ~~the~~ an interior of the processing vessel ~~to be~~ an inert gas environment prior to exhausting of the cleaning fluid from the processing vessel.

18. (Currently Amended) A device for drying substrates as set forth in claim 10, further ~~comprises~~ comprising

~~nozzle position control~~ means for moving the nozzle towards the substrates following exhausting of the cleaning fluid from the processing vessel.

19. (Currently Amended) A device for drying substrates as set forth in claim 10, further comprising

~~circulation~~ means for circulating the drying fluid when ~~ejection is not carried out~~ the means for introducing the drying fluid is not introducing the drying fluid under a liquid condition within the processing vessel.

20. (Currently Amended) A device for drying substrate as set forth in claim 10, wherein

the device for drying substrates has a number of nozzles that is determined in response to ~~the~~ a size of the substrates and ~~the~~ a pitch of the substrates.

21. (Currently Amended) A device for drying substrates as set forth in claim 10, wherein

~~the nozzle has drying fluid~~ ejection blowing holes a number of which is greater than ~~the~~ a number of the substrates by 1 which, and the substrates are dried simultaneously.

22. (Currently Amended) A device for drying substrates as set forth in claim 10, further comprising

~~inert gas supplying~~ means for supplying inert gas to the nozzle so as to flow the drying fluid by ~~the~~ a pressure of the inert gas.

Please add new claims 23-28 as follows:

23. (New) A device for drying substrates comprising:

a processing vessel containing a cleaning fluid;

a substrate supporting section configured to support substrates within the processing vessel;

an exhausting section arranged and configured to lower a fluid face of the cleaning fluid in the processing vessel; and

a drying fluid supplying section arranged and configured to supply a drying fluid onto the fluid face of the cleaning fluid, the drying fluid supplying section having a nozzle dimensioned and configured to form individual liquid drops of the drying fluid and supply the liquid drops of the drying fluid to the fluid face of the cleaning fluid.

24. (New) A device for drying substrates as set forth in claim 23, wherein

the substrate supporting section is configured to support the substrates within the processing vessel in an inclined condition at a predetermined angle with respect to a vertical plane, and the nozzle supplies the liquid drops of the drying fluid with the nozzle inclined at an inclination angle substantially similar to the predetermined angle of the inclined substrates.

25. (New) A device for drying substrates as set forth in claim 23, further comprising

an inert gas supplying section configured to supply an inert gas into the processing vessel.

26. (New) A device for drying substrates as set forth in claim 23, wherein

the substrate supporting section further comprises an upper face with a plurality of supporting grooves therein, and

a slit extending from a bottom section of each of the supporting grooves in a downward direction with respect to the upper face.

27. (New) A device for drying substrates as set forth in claim 23, wherein

the substrate supporting section further comprises

a pair of supporting members arranged and configured to selectively support the substrates at different supporting positions within the processing vessel.

28. (New) A device for drying substrates, comprising
a processing vessel containing a cleaning fluid;
a substrate supporting section configured to support substrates within the processing vessel;

an exhausting section arranged and configured to lower a fluid face of the cleaning fluid within the processing vessel; and

a drying fluid supplying section arranged and configured to supply a drying fluid onto the fluid face of the cleaning fluid, the drying fluid supplying section having a nozzle dimensioned and configured to form liquid drops of the drying fluid having a predetermined range of widths and supply the liquid drops of the drying fluid to the fluid face of the cleaning fluid.